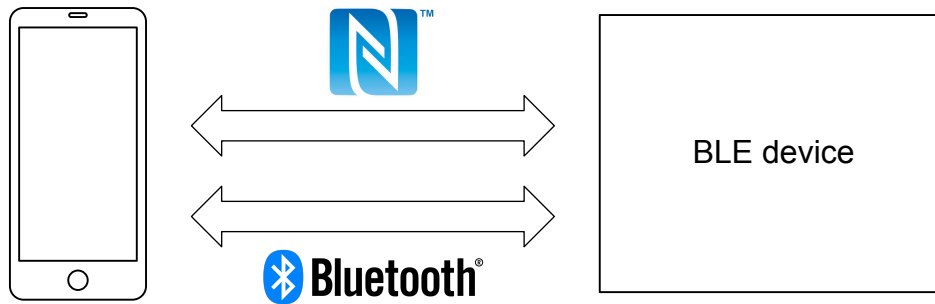


Firmware for Bluetooth® Low Energy out-of-band pairing with NFC

Cover image



Device summary

| Product status |
|----------------|
| STSW-ST25DV013 |

Features

- Bluetooth® Low Energy (BLE) pairing with OOB (out-of-band) information exchanged through NFC using the ST25DV64KC device
- Secure BLE connection
- Secure simple pairing
- Protection against MITM (man-in-the-middle) attacks

Description

ST25DV64KC BLE out-of-band pairing demonstration firmware shows how NFC can be used to improve the security of Bluetooth® Low Energy connections.

NFC provides an additional communication channel between a Bluetooth® device and an Android™ phone. This extra communication channel is used to exchange data (called out-of-band data) used during the Bluetooth pairing, preventing MITM attacks.

An STM32WB55 microcontroller (on the MB1355C board) and an X-NUCLEO-NFC07A1 board are needed to run the demonstration software.

This firmware (STSW-ST25DV013), an Android™ application (STSW-ST25005), its source code (STSW-ST25006), and user manual UM3393 are available on www.st.com.

License

This firmware is delivered under the Mix_MyLiberty software license agreement (SLA0052), and its additional license terms.

Revision history

Table 1. Document revision history

| Date | Version | Changes |
|-------------|---------|------------------|
| 30-Aug-2024 | 1 | Initial release. |

IMPORTANT NOTICE – READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgment.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2024 STMicroelectronics – All rights reserved